10-PG06PPA030SJ02-LH92E08T

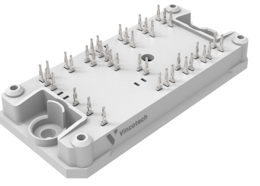
datasheet

***flow*PIM 1 + PFC** **600 V / 30 A**

Features

- Highly integrated PIM with interleaved PFC circuit
- High switching frequency PFC circuit
- On-board capacitors
- New generation high speed IGBTs in the inverter

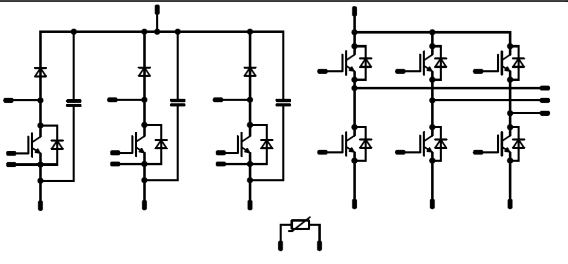
flow 1 12 mm housing



Target applications

- Embedded Drives
- Industrial Drives

Schematic



Types

- 10-PG06PPA030SJ02-LH92E08T

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions		Value	Unit
Inverter Switch					
Collector-emitter voltage	V_{CES}			600	V
Collector current	I_C	$T_j = T_{jmax}$	T_s = 80 °C	30	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}		90	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	63	W
Gate-emitter voltage	V_{GES}			±20	V
Short circuit ratings	t_{SC}	V_{GE} = 15 V, V_{CC} = 400 V	T_j = 150 °C	5	µs
Maximum junction temperature	T_{jmax}			175	°C
Inverter Diode					
Peak repetitive reverse voltage	V_{RRM}			600	V
Continuous (direct) forward current	I_F	$T_j = T_{jmax}$	T_s = 80 °C	28	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}		40	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	50	W
Maximum junction temperature	T_{jmax}			175	°C
PFC Switch					
Collector-emitter voltage	V_{CES}			650	V
Collector current	I_C	$T_j = T_{jmax}$	T_s = 80 °C	27	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}		60	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	56	W
Gate-emitter voltage	V_{GES}			±20	V
Maximum junction temperature	T_{jmax}			175	°C

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions		Value	Unit
PFC Diode					
Peak repetitive reverse voltage	V_{RRM}			650	V
Continuous (direct) forward current	I_F	$T_j = T_{jmax}$	T_s = 80 °C	25	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}		40	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	48	W
Maximum junction temperature	T_{jmax}			175	°C
PFC Sw. Protection Diode					
Peak repetitive reverse voltage	V_{RRM}			650	V
Continuous (direct) forward current	I_F	$T_j = T_{jmax}$	T_s = 80 °C	8	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}		12	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	38	W
Maximum junction temperature	T_{jmax}			175	°C
Capacitor (PFC)					
Maximum DC voltage	V_{MAX}			630	V
Operation Temperature	T_{op}			-55 ... 150	°C

Module Properties

Parameter	Symbol	Conditions		Value	Unit
Thermal Properties					
Storage temperature	T_{stg}			-40…+125	°C
Operation temperature under switching condition	T_{jop}			-40…+(T_{jmax} - 25)	°C
Isolation Properties					
Isolation voltage	V_{isol}	DC Test Voltage*	t_p = 2 s	6000	V
Isolation voltage	V_{isol}	AC Voltage	t_p = 1 min	2500	V
Creepage distance				min. 12,7	mm
Clearance				8,05	mm
Comparative Tracking Index	CTI			≥ 600	

*100 % tested in production

Characteristic Values

Parameter	Symbol	Conditions	V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_{F} [V]	I_{C} [A] I_{D} [A] I_{F} [A]	T_{j} [°C]	Min	Typ	Max	Unit
Inverter Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}$			0,0005	25	4,1	5,1	5,7	V
Collector-emitter saturation voltage	V_{CEsat}		15		30	25 125 150		1,73 1,97 2,01	1,8	V
Collector-emitter cut-off current	I_{CES}		0	600		25			1,6	μA
Gate-emitter leakage current	I_{GES}		20	0		25			100	nA
Internal gate resistance	r_{g}							None		Ω
Input capacitance	C_{ies}	f = 1 Mhz	0	25		25		1050		pF
Output capacitance	C_{oes}							45		pF
Reverse transfer capacitance	C_{res}							36		pF
Gate charge	Q_{g}	V_{CC} = 480 V	15		30	25		130		nC
Thermal										
Thermal resistance junction to sink*	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,52		K/W

*Only valid with pre-applied Vincotech thermal interface material.

Parameter	Symbol	Conditions	V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_{F} [V]	I_{C} [A] I_{D} [A] I_{F} [A]	T_{j} [°C]	Min	Typ	Max	Unit
Dynamic										
Turn-on delay time	$t_{d(on)}$	R_{gon} = 8 Ω R_{goff} = 8 Ω	±15	350	30	25 125 150		37 38 38		ns
Rise time	t_{r}					25 125 150		12 13 15		ns
Turn-off delay time	$t_{d(off)}$					25 125 150		90 109 113		ns
Fall time	t_{f}					25 125 150		12 19,35 23,06		ns
Turn-on energy (per pulse)	E_{on}	Q_{rFWD}=0,812 μC Q_{rFWD}=1,81 μC Q_{rFWD}=2,02 μC				25 125 150		0,758 0,981 1,04		mWs
Turn-off energy (per pulse)	E_{off}					25 125 150		0,233 0,422 0,469		mWs

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Inverter Diode										
Static										
Forward voltage	V_F				20	25 125	1,25	1,71 1,58	1,95	V
Reverse leakage current	I_R	V_r = 600 V				25			27	µA
Thermal										
Thermal resistance junction to sink*	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,91		K/W

*Only valid with pre-applied Vincotech thermal interface material.

Parameter	Symbol	Conditions	V_{GE} [V]	V_{CE} [V]	I_C [A]	T_j [°C]	Min	Typ	Max	Unit
Dynamic										
Peak recovery current	I_{RRM}	d*i*/d*t*=500 A/µs d*i*/d*t*=1295 A/µs d*i*/d*t*=1294 A/µs	±15	350	30	25 125 150		7,86 12,39 13,22		A
Reverse recovery time	t_{rr}					25 125 150		200,95 276,23 327,76		ns
Recovered charge	Q_r					25 125 150		0,812 1,81 2,02		µC
Reverse recovered energy	E_{rec}					25 125 150		0,161 0,388 0,431		mWs
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25 125 150		53,57 61,27 82,45		A/µs

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
PFC Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}$			0,0002	25	3,3	4	4,7	V
Collector-emitter saturation voltage	V_{CEsat}		15		20	25 125 150		1,54 1,69 1,74	2,22	V
Collector-emitter cut-off current	I_{CES}		0	650		25			40	µA
Gate-emitter leakage current	I_{GES}		20	0		25			120	nA
Internal gate resistance	r_g							None		Ω
Input capacitance	C_{ies}	f = 1 Mhz	0	25		25		1200		pF
Output capacitance	C_{oes}							30		pF
Reverse transfer capacitance	C_{res}							5		pF
Gate charge	Q_g	V_{CC} = 520 V	15		20	25		48		nC
Thermal										
Thermal resistance junction to sink*	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,7		K/W

*Only valid with pre-applied Vincotech thermal interface material.

Parameter	Symbol	Conditions	V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	Unit
Dynamic										
Turn-on delay time	$t_{d(on)}$	R_{gon} = 16 Ω R_{goff} = 16 Ω	0/15	400	20	25 125 150		17 19 13		ns
Rise time	t_r					25 125 150		9 11 9		ns
Turn-off delay time	$t_{d(off)}$					25 125 150		99 115 120		ns
Fall time	t_f					25 125 150		8,08 13,64 10,32		ns
Turn-on energy (per pulse)	E_{on}	Q_{rFWD}=0,307 µC Q_{rFWD}=0,491 µC Q_{rFWD}=0,612 µC				25 125 150		0,315 0,36 0,47		mWs
Turn-off energy (per pulse)	E_{off}					25 125 150		0,064 0,146 0,11		mWs

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
PFC Diode										
Static										
Forward voltage	V_F				20	25 125 150		1,82 1,8 1,76	2,22	V
Reverse leakage current	I_R	V_r = 650 V				25			1,28	µA
Thermal										
Thermal resistance junction to sink*	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,96		K/W

*Only valid with pre-applied Vincotech thermal interface material.

Parameter	Symbol	Conditions	V_{GE} [V]	V_{CE} [V]	I_C [A]	T_j [°C]	Min	Typ	Max	Unit
Dynamic										
Peak recovery current	I_{RRM}	di/dt=2664 A/µs di/dt=2094 A/µs di/dt=2443 A/µs	0/15	400	20	25 125 150		15,35 19,92 24		A
Reverse recovery time	t_{rr}					25 125 150		32,73 40,14 41,74		ns
Recovered charge	Q_r					25 125 150		0,307 0,491 0,612		µC
Reverse recovered energy	E_{rec}					25 125 150		0,06 0,109 0,097		mWs
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25 125 150		848,64 985,81 965,97		A/µs

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
PFC Sw. Protection Diode										
Static										
Forward voltage	V_F				6	25 125 150	1,23	1,72 1,58 1,53	1,87	V
Reverse leakage current	I_R	V_r = 650 V				25			0,1	µA
Thermal										
Thermal resistance junction to sink*	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						2,53		K/W

*Only valid with pre-applied Vincotech thermal interface material.

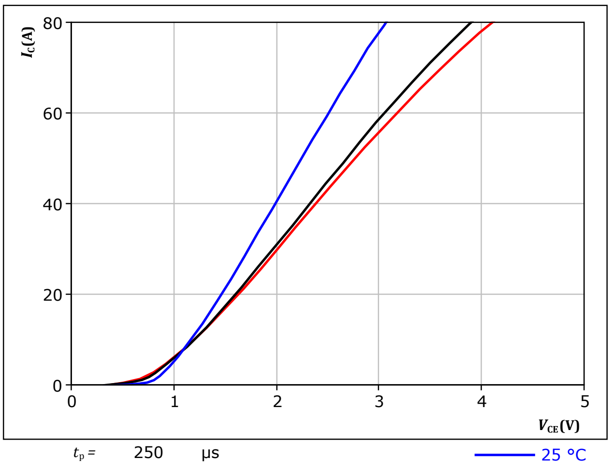
Parameter	Symbol	Conditions					Min	Typ	Max	Unit
Capacitor (PFC)										
Static										
Capacitance	C							33		nF
Tolerance							-5		5	%
Thermistor										
Static										
Rated resistance	R					25		22		kΩ
Deviation of R_{100}	$\Delta_{R/R}$	R_{100} = 1484 Ω				100	-5		5	%
Power dissipation	P							5		mW
Power dissipation constant	d					25		1,5		mW/K
B-value	$B_{(25/50)}$	Tol. ±1 %						3962		K
B-value	$B_{(25/100)}$	Tol. ±1 %						4000		K
Vincotech Thermistor Reference									I	

Inverter Switch Characteristics

figure 1. IGBT

Typical output characteristics

$I_C = f(V_{CE})$

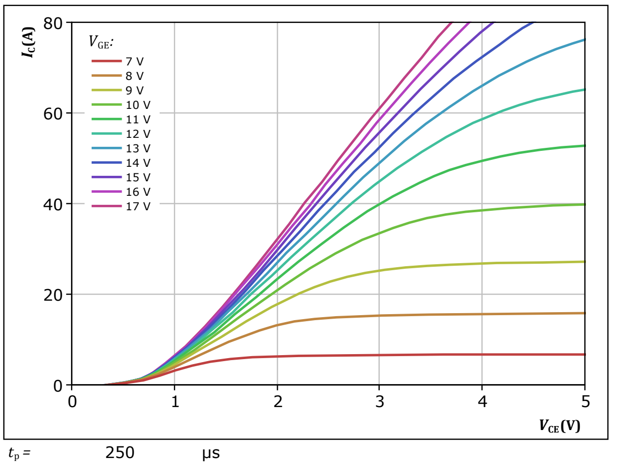


t_p = 250 µs
V_{GE} = 15 V
T_j: 25 °C, 125 °C, 150 °C

figure 2. IGBT

Typical output characteristics

$I_C = f(V_{CE})$

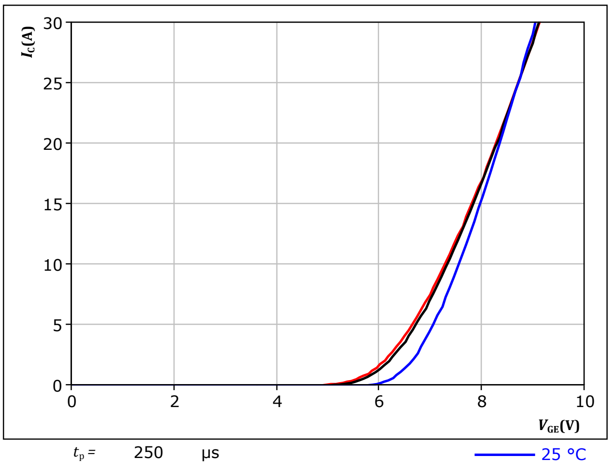


t_p = 250 µs
T_j = 150 °C
V_{GE} from 7 V to 17 V in steps of 1 V

figure 3. IGBT

Typical transfer characteristics

$I_C = f(V_{GE})$

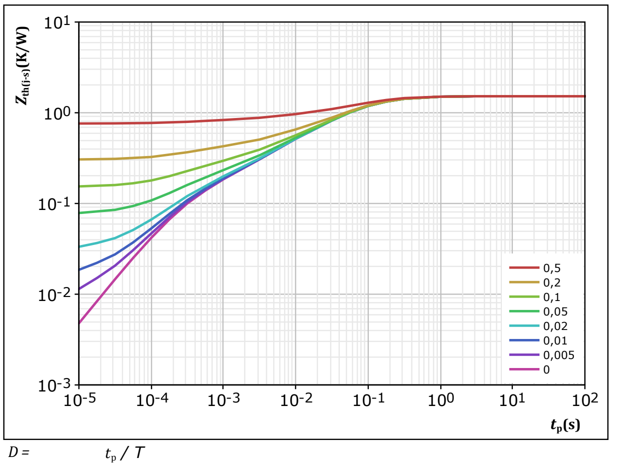


t_p = 250 µs
V_{CE} = 10 V
T_j: 25 °C, 125 °C, 150 °C

figure 4. IGBT

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



D = t_p / T
$R_{th(j-s)}$ = 1,52 K/W

IGBT thermal model values

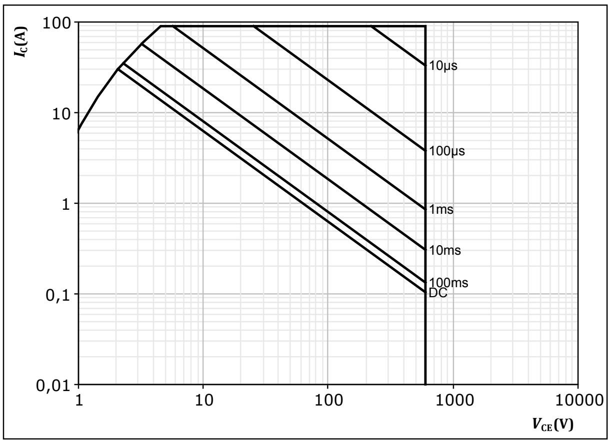
R (K/W)	τ (s)
1,77E-01	4,26E-01
6,88E-01	7,72E-02
3,07E-01	2,26E-02
2,02E-01	5,04E-03
6,94E-02	7,36E-04
7,56E-02	2,30E-04

Inverter Switch Characteristics

figure 5. **IGBT**

Safe operating area

$I_C = f(V_{CE})$



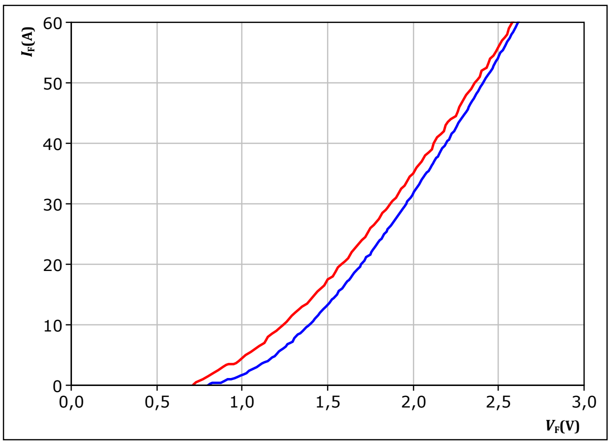
D =	single pulse	
T_s =	80	°C
V_{GE} =	15	V
T_j =	T_{jmax}	

Inverter Diode Characteristics

figure 6.	FWD

Typical forward characteristics

I_F = f(V_F)



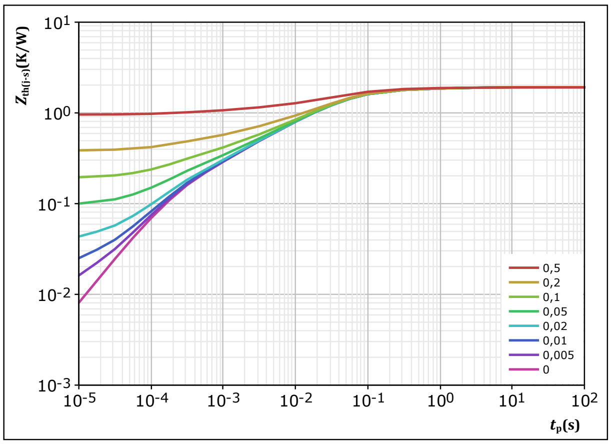
t_p = 250 µs

T_j: 25 °C, 125 °C

figure 7.	FWD

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)}$ = f(t_p)



D = t_p / T

$R_{th(j-s)}$ = 1,914 K/W

IGBT thermal model values

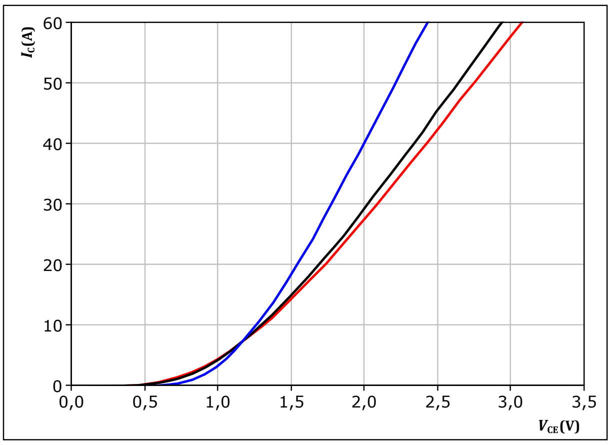
R (K/W)	τ (s)
8,07E-02	2,21E+00
2,18E-01	2,22E-01
8,50E-01	4,41E-02
4,32E-01	9,35E-03
2,00E-01	1,60E-03
1,34E-01	2,12E-04

PFC Switch Characteristics

figure 8. IGBT

Typical output characteristics

$I_C = f(V_{CE})$

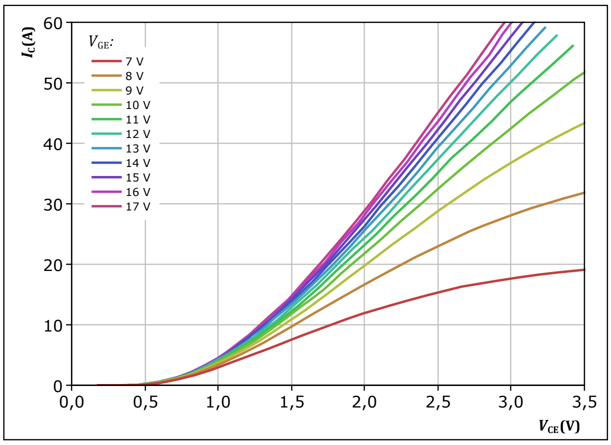


t_p = 250 µs
V_{GE} = 15 V
T_j: 25 °C, 125 °C, 150 °C

figure 9. IGBT

Typical output characteristics

$I_C = f(V_{CE})$

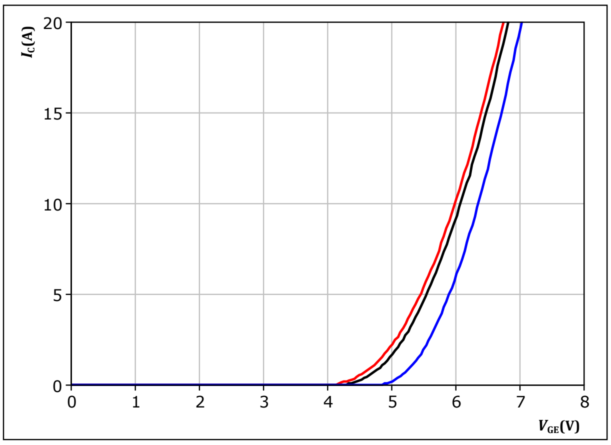


t_p = 250 µs
T_j = 150 °C
V_{GE} from 7 V to 17 V in steps of 1 V

figure 10. IGBT

Typical transfer characteristics

$I_C = f(V_{GE})$

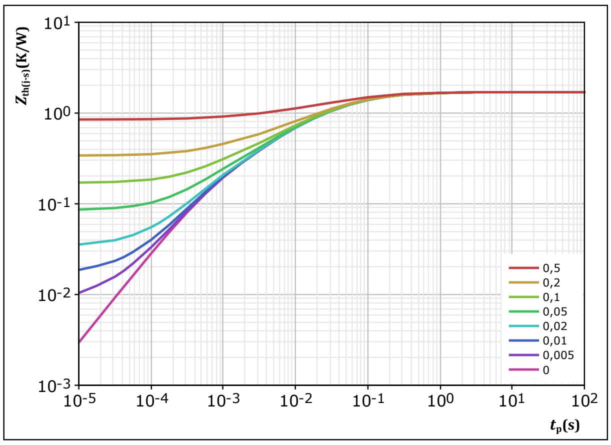


t_p = 250 µs
V_{CE} = 10 V
T_j: 25 °C, 125 °C, 150 °C

figure 11. IGBT

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



$D = t_p / T$
$R_{th(j-s)}$ = 1,698 K/W

IGBT thermal model values

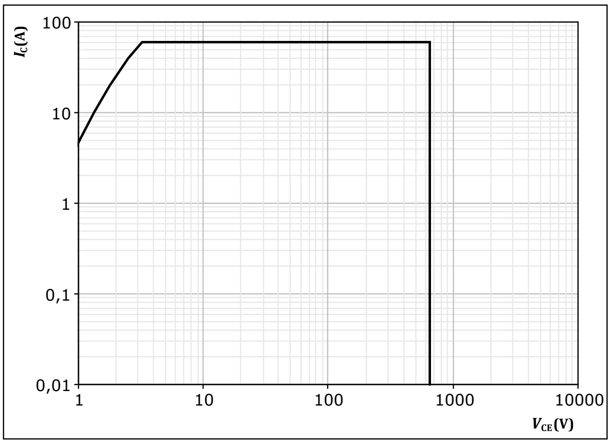
R (K/W)	τ (s)
1,45E-01	7,07E-01
5,50E-01	8,69E-02
5,51E-01	2,05E-02
3,26E-01	4,56E-03
1,26E-01	6,55E-04

PFC Switch Characteristics

figure 12.	**IGBT**

Safe operating area

$I_C = f(V_{CE})$



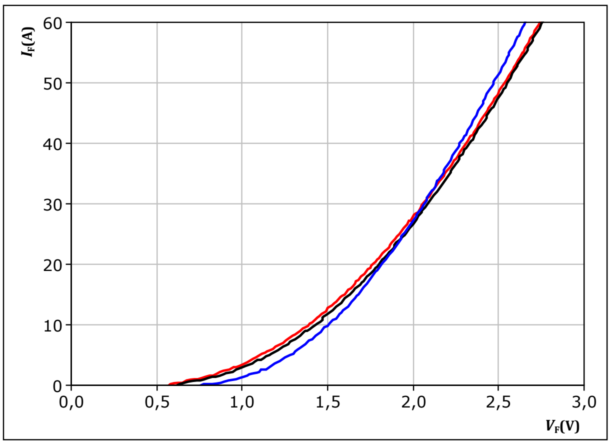
D =	single pulse	
T_s =	80	°C
V_{GE} =	15	V
T_j =	T_{jmax}	

PFC Diode Characteristics

figure 13. **FWD**

Typical forward characteristics

I_F = f(V_F)



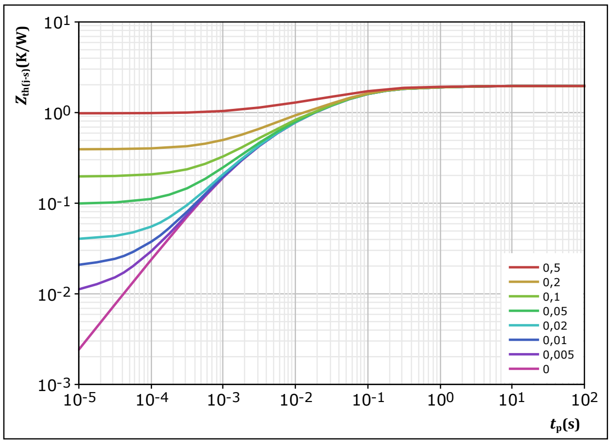
t_p = 250 µs

T_j: 25 °C, 125 °C, 150 °C

figure 14. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)}$ = f(t_p)



D = t_p / T

$R_{th(j-s)}$ = 1,964 K/W

IGBT thermal model values

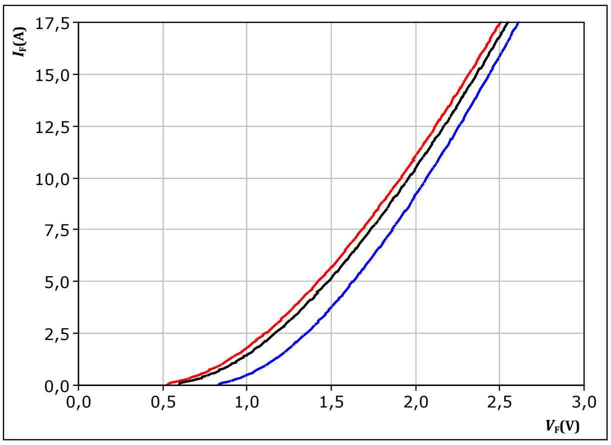
R (K/W)	τ (s)
1,07E-01	1,92E+00
3,62E-01	1,49E-01
7,68E-01	4,26E-02
5,43E-01	7,00E-03
1,84E-01	1,27E-03

PFC Sw. Protection Diode Characteristics

figure 15. FWD

Typical forward characteristics

I_F = f(V_F)



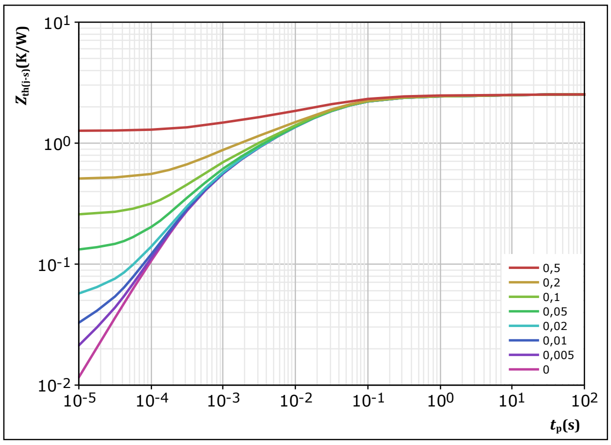
t_p = 250 μs

T_j: 25 °C, 125 °C, 150 °C

figure 16. FWD

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)}$ = f(t_p)



D = t_p / T

$R_{th(j-s)}$ = 2,527 K/W

IGBT thermal model values

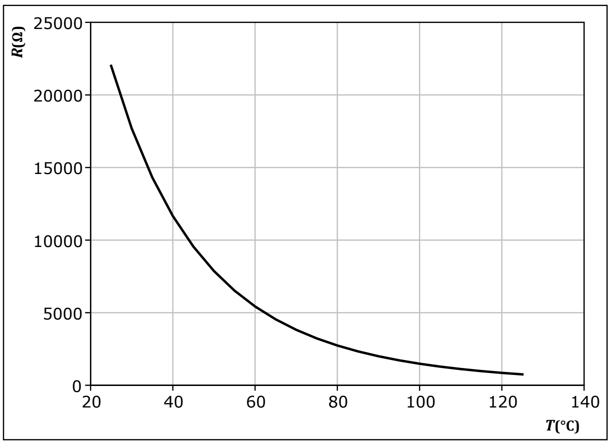
R (K/W)	τ (s)
9,24E-02	9,29E+00
1,75E-01	3,21E-01
7,31E-01	4,97E-02
7,14E-01	1,16E-02
4,89E-01	2,11E-03
3,27E-01	3,78E-04

Thermistor Characteristics

figure 17. **Thermistor**

Typical NTC characteristic as function of temperature

R_T = f(T)

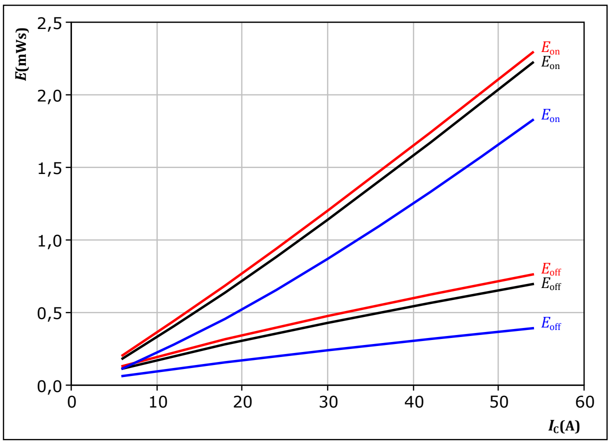


Inverter Switching Characteristics

figure 18. **IGBT**

Typical switching energy losses as a function of collector current

$E = f(I_C)$



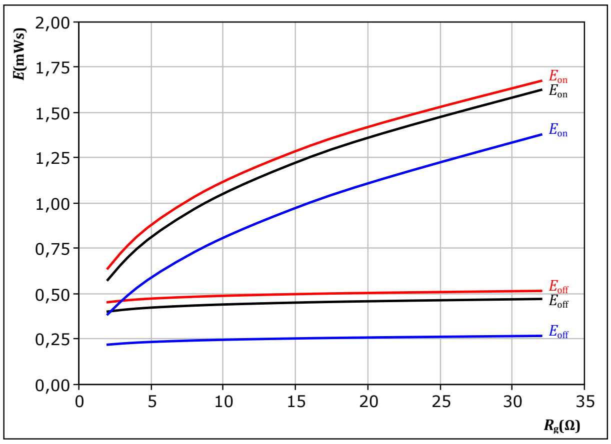
With an inductive load at

V_{CE} =	350	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	8	Ω		150 °C
R_{goff} =	8	Ω		

figure 19. **IGBT**

Typical switching energy losses as a function of gate resistor

$E = f(R_g)$



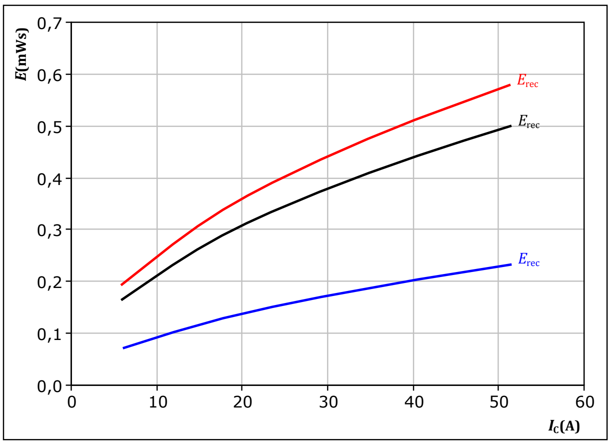
With an inductive load at

V_{CE} =	350	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	30	A		150 °C

figure 20. **FWD**

Typical reverse recovered energy loss as a function of collector current

$E_{rec} = f(I_C)$



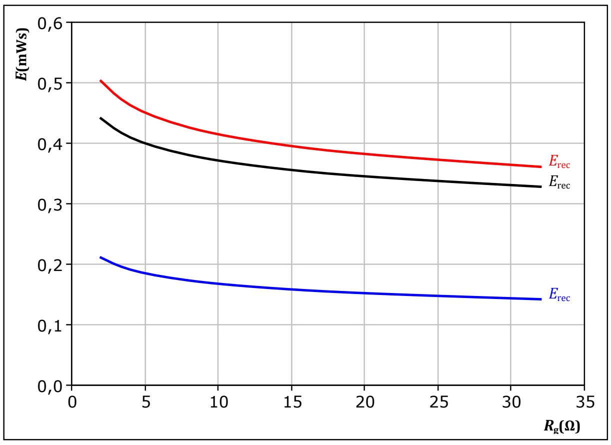
With an inductive load at

V_{CE} =	350	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	8	Ω		150 °C

figure 21. **FWD**

Typical reverse recovered energy loss as a function of gate resistor

$E_{rec} = f(R_g)$



With an inductive load at

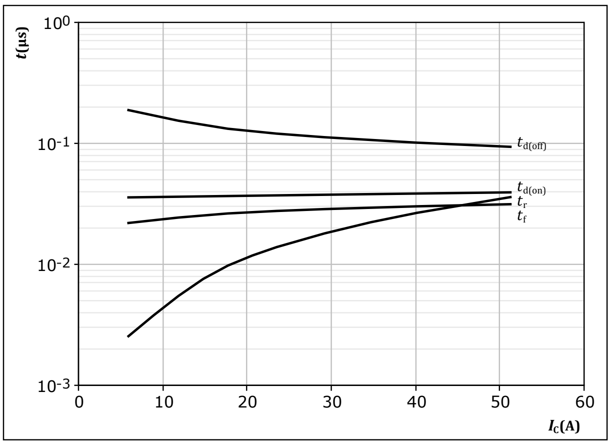
V_{CE} =	350	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	30	A		150 °C

Inverter Switching Characteristics

figure 22. **IGBT**

Typical switching times as a function of collector current

$t = f(I_C)$



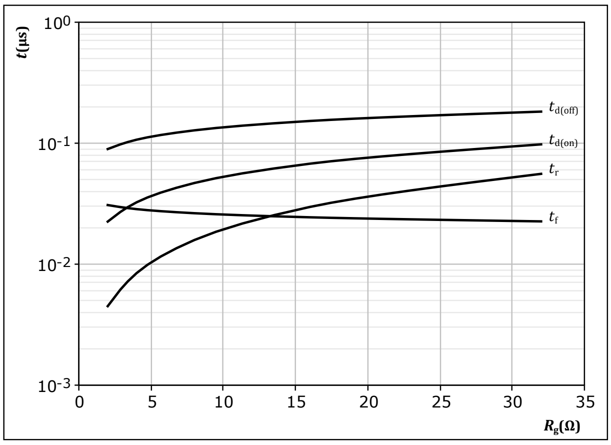
With an inductive load at

T_j =	150	°C
V_{CE} =	350	V
V_{GE} =	±15	V
R_{gon} =	8	Ω
R_{goff} =	8	Ω

figure 23. **IGBT**

Typical switching times as a function of gate resistor

$t = f(R_g)$



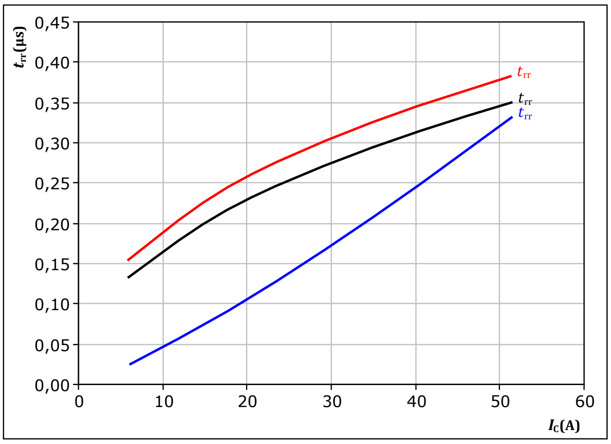
With an inductive load at

T_j =	150	°C
V_{CE} =	350	V
V_{GE} =	±15	V
I_C =	30	A

figure 24. **FWD**

Typical reverse recovery time as a function of collector current

$t_{rr} = f(I_C)$



With an inductive load at

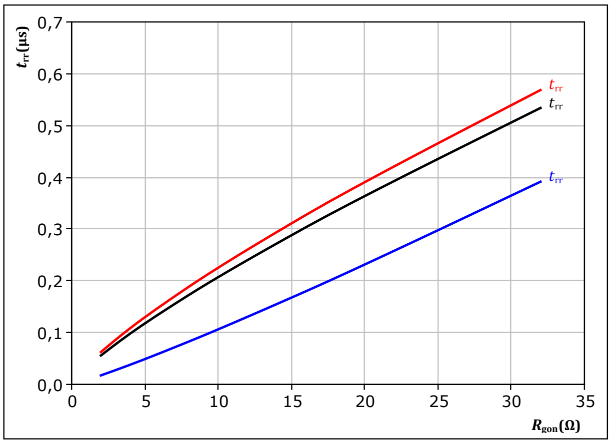
V_{CE} =	350	V
V_{GE} =	±15	V
R_{gon} =	8	Ω

T_j: 25 °C, 125 °C, 150 °C

figure 25. **FWD**

Typical reverse recovery time as a function of IGBT turn on gate resistor

$t_{rr} = f(R_{gon})$



With an inductive load at

V_{CE} =	350	V
V_{GE} =	±15	V
I_C =	30	A

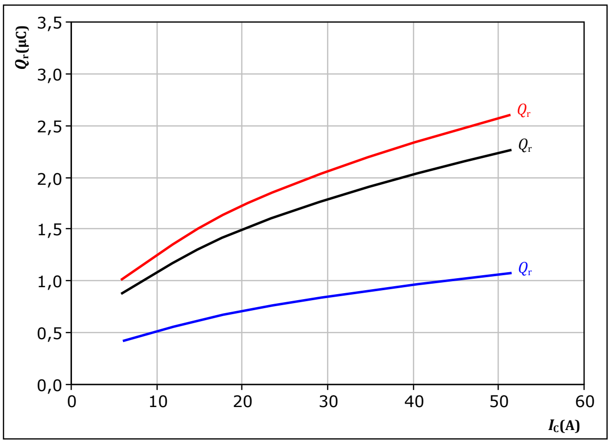
T_j: 25 °C, 125 °C, 150 °C

Inverter Switching Characteristics

figure 26. FWD

Typical recovered charge as a function of collector current

$Q_r = f(I_C)$



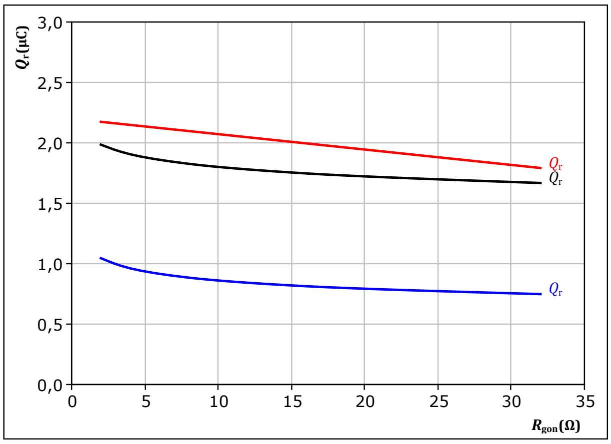
With an inductive load at

V_{CE} =	350	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	8	Ω		150 °C

figure 27. FWD

Typical recovered charge as a function of turn on gate resistor

$Q_r = f(R_{gon})$



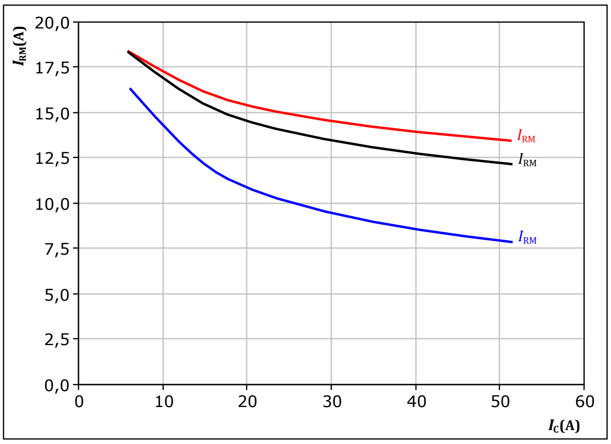
With an inductive load at

V_{CE} =	350	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	30	A		150 °C

figure 28. FWD

Typical peak reverse recovery current as a function of collector current

$I_{RM} = f(I_C)$



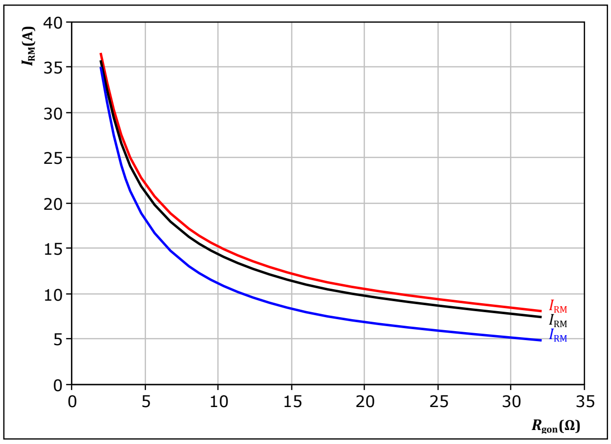
With an inductive load at

V_{CE} =	350	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	8	Ω		150 °C

figure 29. FWD

Typical peak reverse recovery current as a function of turn on gate resistor

$I_{RM} = f(R_{gon})$



With an inductive load at

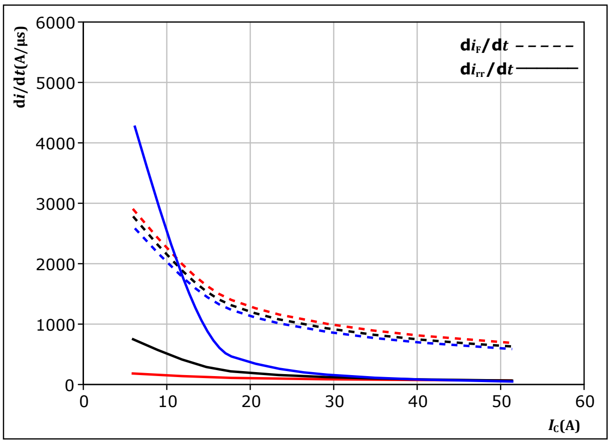
V_{CE} =	350	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	30	A		150 °C

Inverter Switching Characteristics

figure 30. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of collector current

di_F/dt, di_{rr}/dt = f(I_C)



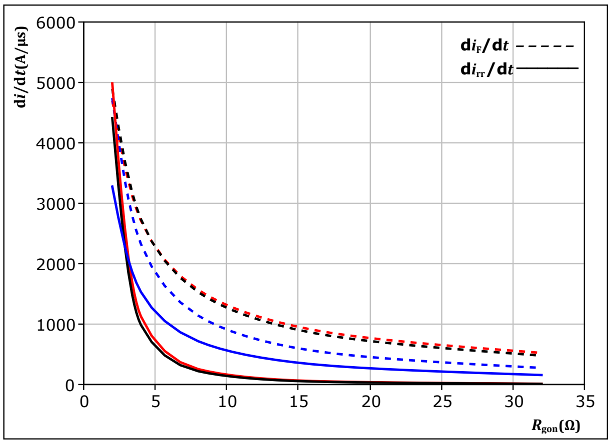
With an inductive load at

V_{CE} =	350	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	8	Ω		150 °C

figure 31. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of turn on gate resistor

di_F/dt, di_{rr}/dt = f(R_{gon})



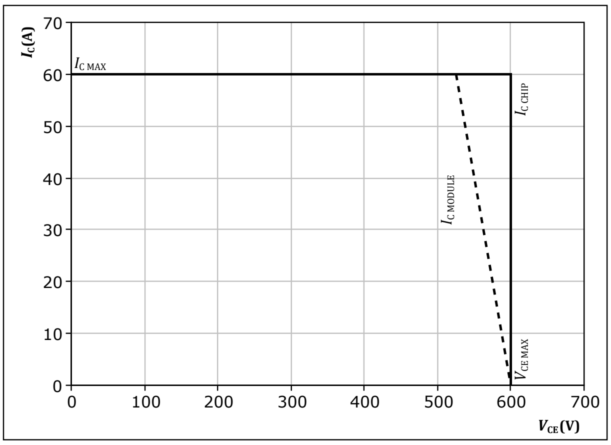
With an inductive load at

V_{CE} =	350	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	30	A		150 °C

figure 32. **IGBT**

Reverse bias safe operating area

I_C = f(V_{CE})



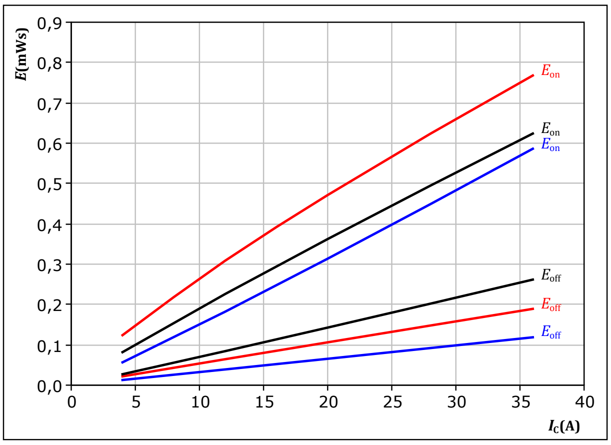
At	T_j =	150	°C
	R_{gon} =	8	Ω
	R_{goff} =	8	Ω

PFC Switching Characteristics

figure 33. **IGBT**

Typical switching energy losses as a function of collector current

$E = f(I_C)$



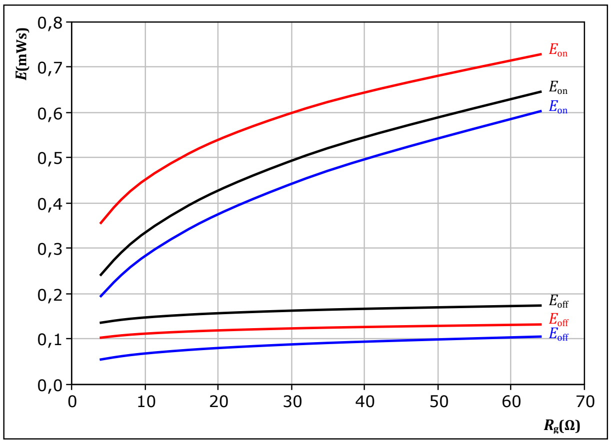
With an inductive load at

V_{CE} =	400	V	T_j:	25 °C
V_{GE} =	0/15	V		125 °C
R_{gon} =	16	Ω		150 °C
R_{goff} =	16	Ω		

figure 34. **IGBT**

Typical switching energy losses as a function of gate resistor

$E = f(R_g)$



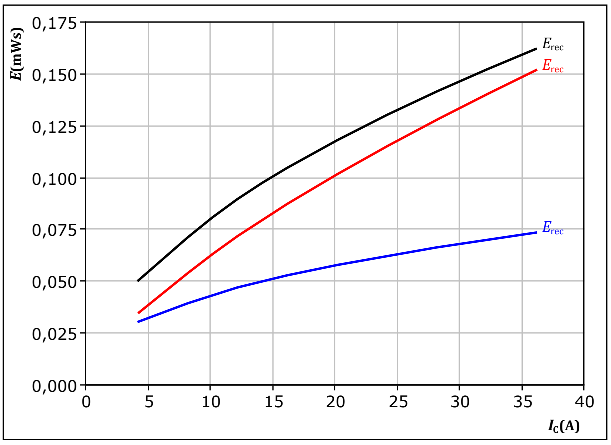
With an inductive load at

V_{CE} =	400	V	T_j:	25 °C
V_{GE} =	0/15	V		125 °C
I_C =	20	A		150 °C

figure 35. **FWD**

Typical reverse recovered energy loss as a function of collector current

$E_{rec} = f(I_C)$



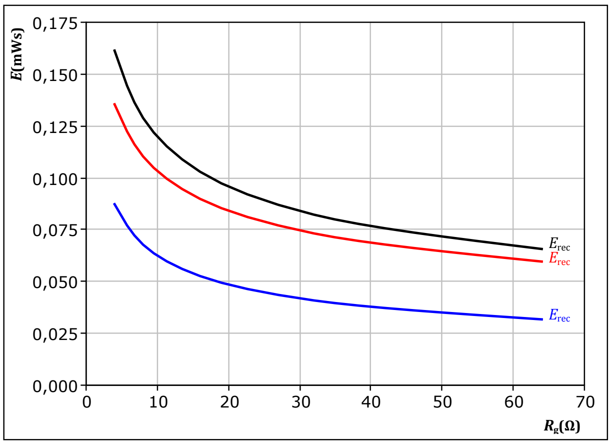
With an inductive load at

V_{CE} =	400	V	T_j:	25 °C
V_{GE} =	0/15	V		125 °C
R_{gon} =	16	Ω		150 °C

figure 36. **FWD**

Typical reverse recovered energy loss as a function of gate resistor

$E_{rec} = f(R_g)$



With an inductive load at

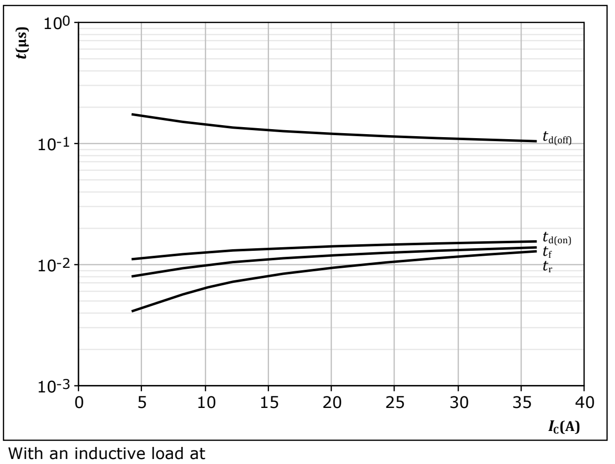
V_{CE} =	400	V	T_j:	25 °C
V_{GE} =	0/15	V		125 °C
I_C =	20	A		150 °C

PFC Switching Characteristics

figure 37. **IGBT**

Typical switching times as a function of collector current

$t = f(I_C)$



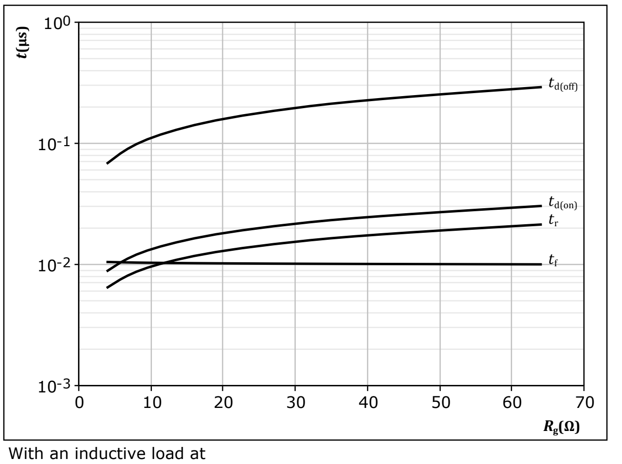
With an inductive load at

T_j =	150	°C
V_{CE} =	400	V
V_{GE} =	0/15	V
R_{gon} =	16	Ω
R_{goff} =	16	Ω

figure 38. **IGBT**

Typical switching times as a function of gate resistor

$t = f(R_g)$



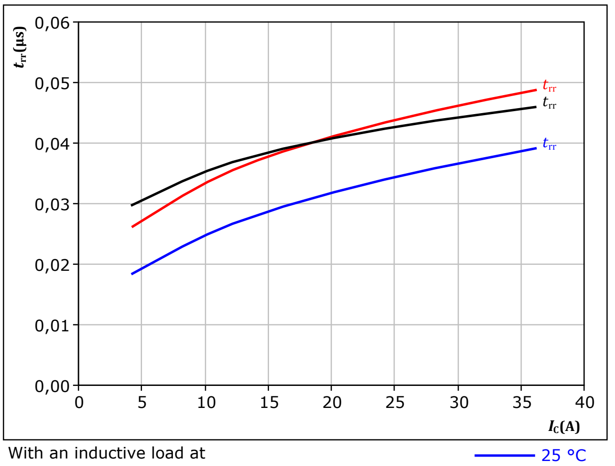
With an inductive load at

T_j =	150	°C
V_{CE} =	400	V
V_{GE} =	0/15	V
I_C =	20	A

figure 39. **FWD**

Typical reverse recovery time as a function of collector current

$t_{rr} = f(I_C)$



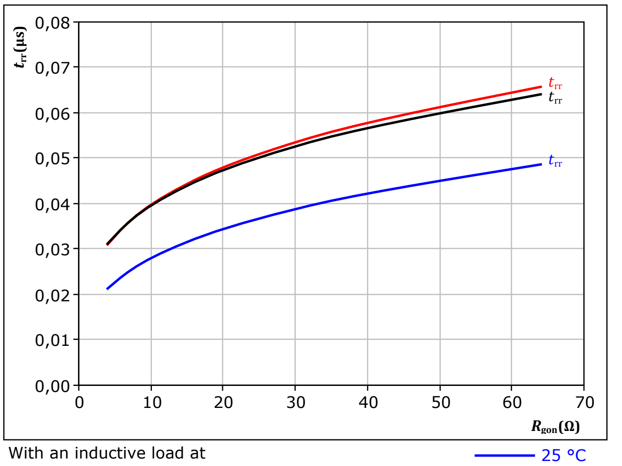
With an inductive load at

V_{CE} =	400	V
V_{GE} =	0/15	V
R_{gon} =	16	Ω

figure 40. **FWD**

Typical reverse recovery time as a function of IGBT turn on gate resistor

$t_{rr} = f(R_{gon})$



With an inductive load at

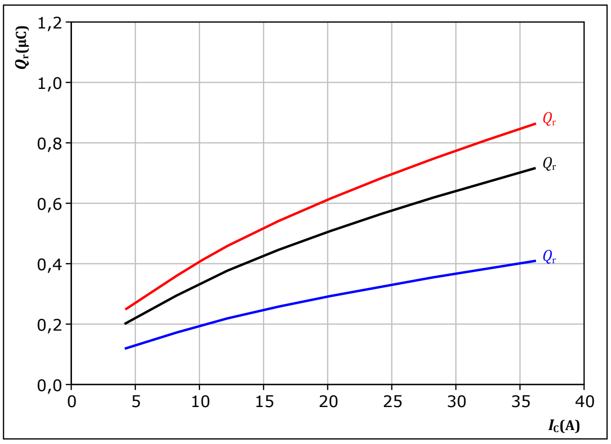
V_{CE} =	400	V
V_{GE} =	0/15	V
I_C =	20	A

PFC Switching Characteristics

figure 41. **FWD**

Typical recovered charge as a function of collector current

$Q_r = f(I_C)$



With an inductive load at

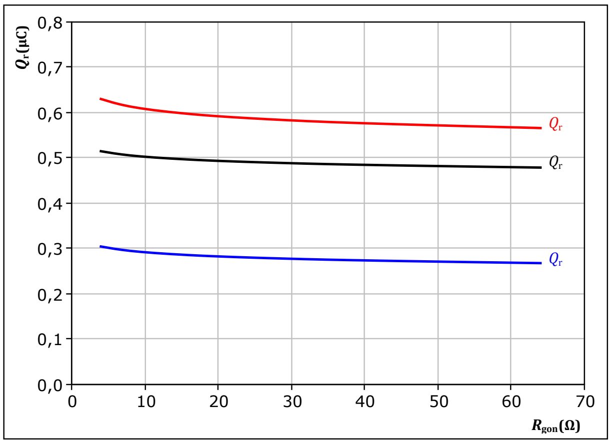
V_{CE} = 400 V
V_{GE} = 0/15 V
R_{gon} = 16 Ω

T_j: 25 °C, 125 °C, 150 °C

figure 42. **FWD**

Typical recovered charge as a function of turn on gate resistor

$Q_r = f(R_{gon})$



With an inductive load at

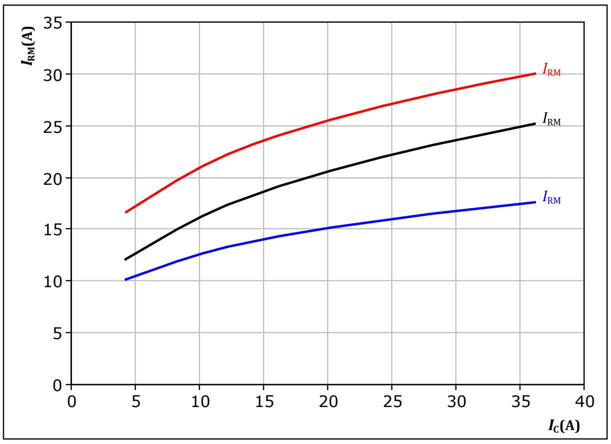
V_{CE} = 400 V
V_{GE} = 0/15 V
I_C = 20 A

T_j: 25 °C, 125 °C, 150 °C

figure 43. **FWD**

Typical peak reverse recovery current as a function of collector current

$I_{RM} = f(I_C)$



With an inductive load at

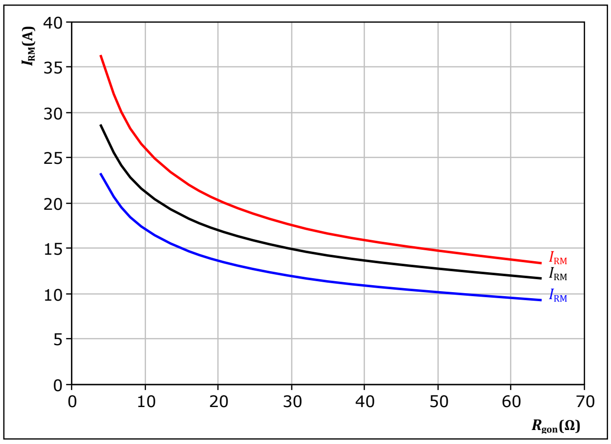
V_{CE} = 400 V
V_{GE} = 0/15 V
R_{gon} = 16 Ω

T_j: 25 °C, 125 °C, 150 °C

figure 44. **FWD**

Typical peak reverse recovery current as a function of turn on gate resistor

$I_{RM} = f(R_{gon})$



With an inductive load at

V_{CE} = 400 V
V_{GE} = 0/15 V
I_C = 20 A

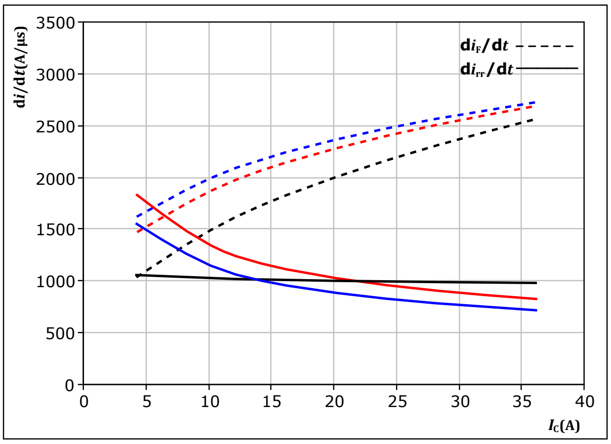
T_j: 25 °C, 125 °C, 150 °C

PFC Switching Characteristics

figure 45. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of collector current

di_F/dt, di_{rr}/dt = f(I_C)



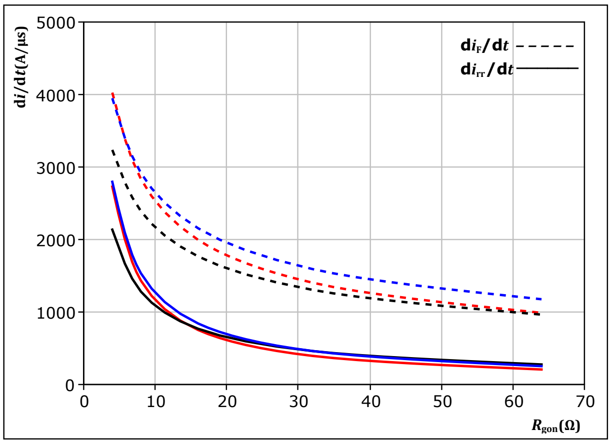
With an inductive load at

V_{CE} =	400	V	T_j: 25 °C / 125 °C / 150 °C
V_{GE} =	0/15	V	
R_{gon} =	16	Ω	

figure 46. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of turn on gate resistor

di_F/dt, di_{rr}/dt = f(R_{gon})



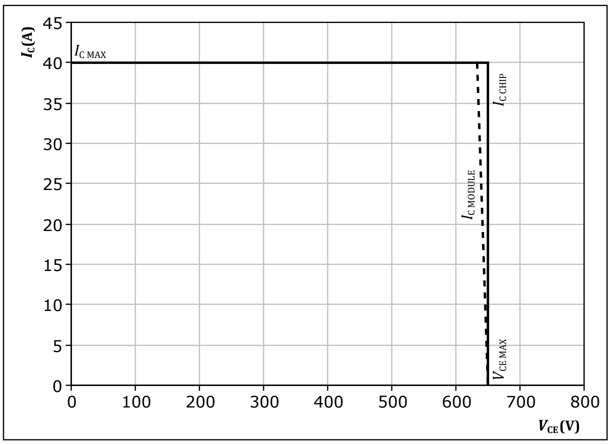
With an inductive load at

V_{CE} =	400	V	T_j: 25 °C / 125 °C / 150 °C
V_{GE} =	0/15	V	
I_C =	20	A	

figure 47. **IGBT**

Reverse bias safe operating area

I_C = f(V_{CE})



At	T_j =	150	°C
	R_{gon} =	16	Ω
	R_{goff} =	16	Ω

Switching Definitions

figure 48. **IGBT**

Turn-off Switching Waveforms & definition of t_{doff}, t_{Eoff} (t_{tEoff} **= integrating time for** E_{off})

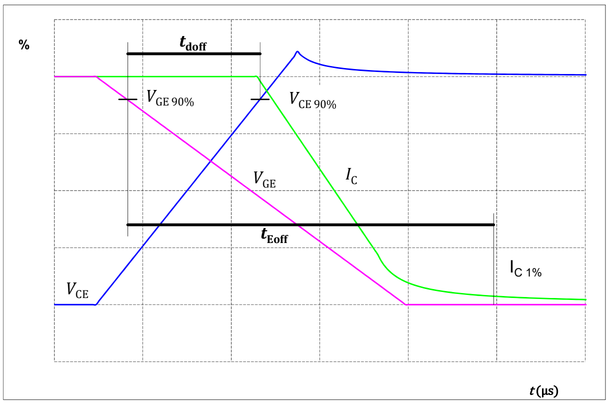


figure 49. **IGBT**

Turn-on Switching Waveforms & definition of t_{don}, t_{Eon} (t_{Eon} **= integrating time for** E_{on})

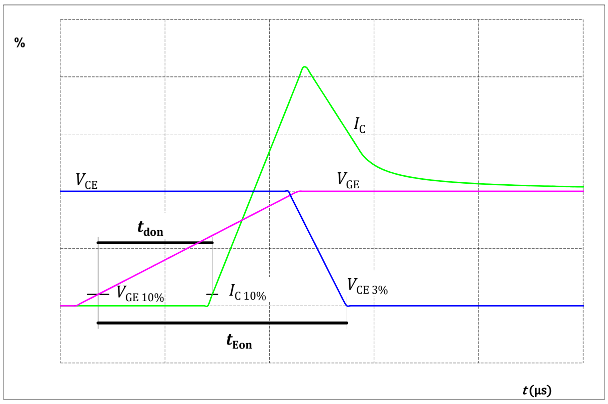


figure 50. **IGBT**

Turn-off Switching Waveforms & definition of t_f

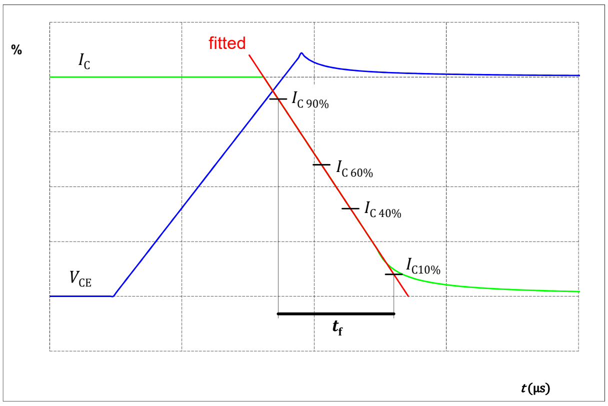
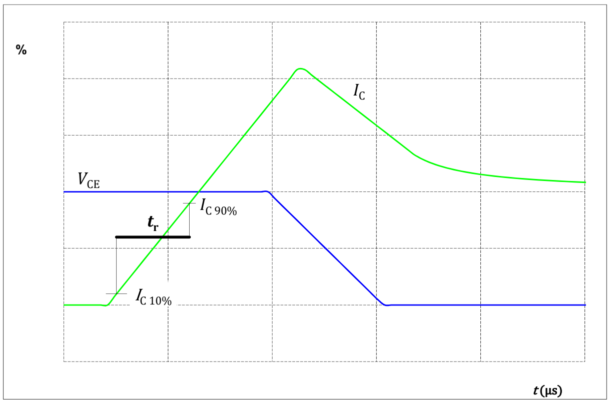


figure 51. **IGBT**

Turn-on Switching Waveforms & definition of t_r



Switching Definitions

figure 52. **FWD**

Turn-off Switching Waveforms & definition of t_{rr}

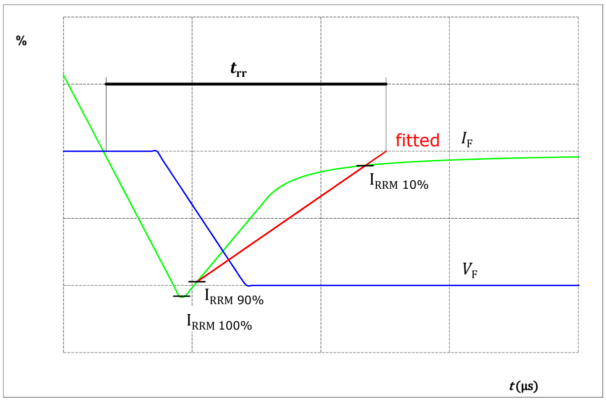
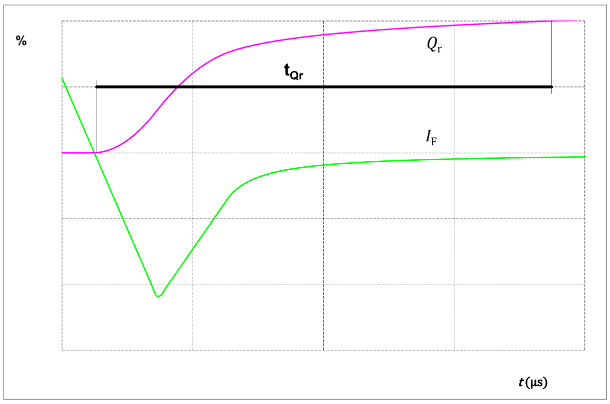


figure 53. **FWD**

Turn-on Switching Waveforms & definition of t_{Qr} **(** t_{Qr} **= integrating time for** Q_r**)**



Ordering Code

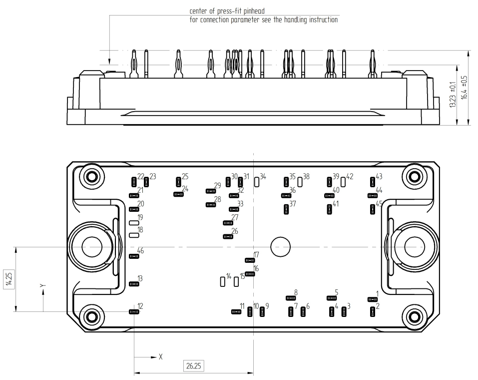
Version	Ordering Code
Without thermal paste	10-PG06PPA030SJ02-LH92E08T
With thermal paste	10-PG06PPA030SJ02-LH92E08T-/3/

Marking

	Name		Date code	UL & VIN	Lot	Serial
Text	NN-NNNNNNNNNNNNNN-TTTTTTVV		WWYY	UL VIN	LLLLL	SSSS
	Type&Ver	**Lot number**	**Serial**	**Date code**		
Datamatrix	TTTTTTTVV	LLLLL	SSSS	WWYY		

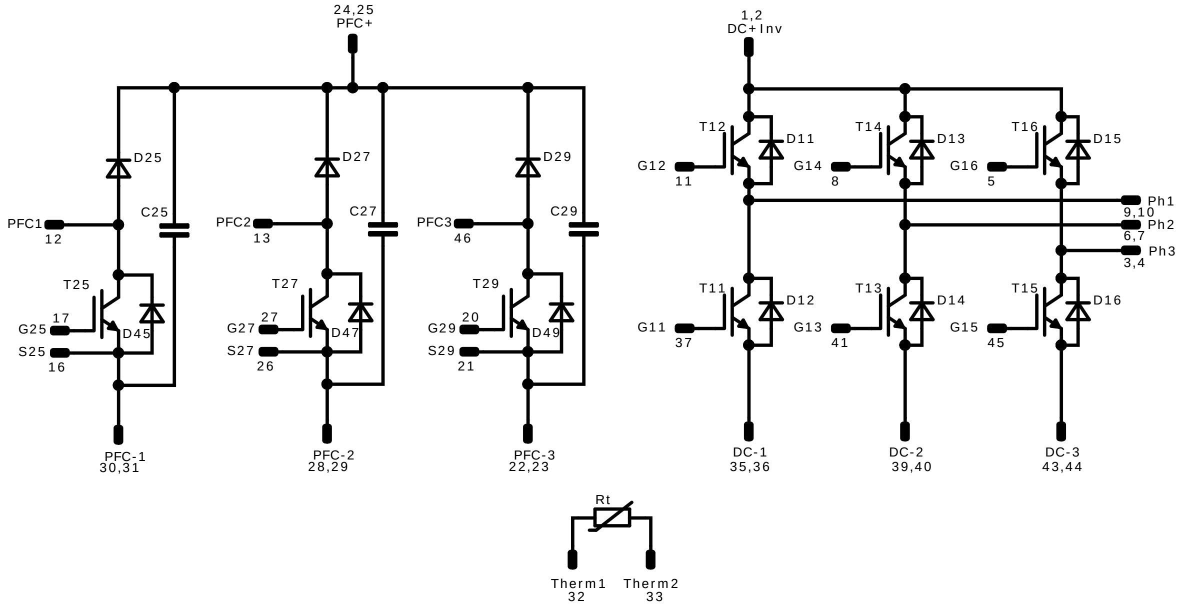
Outline

Pin table [mm]			
Pin	X	Y	Function
1	52,5	2,7	DC+Inv
2	52,5	0	DC+Inv
3	46,2	0	Ph3
4	43,5	0	Ph3
5	43,5	3	G16
6	37,2	0	Ph2
7	34,5	0	Ph2
8	34,5	3	G14
9	28,2	0	Ph1
10	25,5	0	Ph1
11	22,5	0	G12
12	0	0	PFC1
13	0	6,1	PFC2
14	not assembled		
15	not assembled		
16	25,5	8,3	S25
17	25,5	11,3	G25
18	not assembled		
19	not assembled		
20	0	22,5	G29
21	0	25,5	S29
22	0	28,5	PFC-3
23	2,7	28,5	PFC-3
24	9,8	25,8	PFC+
25	9,8	28,5	PFC+
26	20,7	16,5	S27
27	20,7	19,5	G27
28	16,9	23,5	PFC-2
29	16,9	26,5	PFC-2
30	20,7	28,5	PFC-1
31	23,4	28,5	PFC-1
32	22	25,5	Therm1
33	22	22,5	Therm2
34	not assembled		
35	33,5	28,5	DC-1
36	33,5	25,5	DC-1
37	33,5	22,5	G11
38	not assembled		
39	43	28,5	DC-2
40	43	25,5	DC-2
41	43	22,5	G13
42	not assembled		
43	52,5	28,5	DC-3
44	52,5	25,5	DC-3
45	52,5	22,5	G15
46	0	12,2	PFC3



Tolerance of pinpositions: ±0.4mm at the end of pins
Dimension of coordinate axis is only offset without tolerance

Pinout



Identification

ID	Component	Voltage	Current	Function	Comment
T11, T12, T13, T14, T15, T16	IGBT	600 V	30 A	Inverter Switch	
D11, D12, D13, D14, D15, D16	FWD	600 V	20 A	Inverter Diode	
T25, T27, T29	IGBT	650 V	20 A	PFC Switch	
D25, D27, D29	FWD	650 V	20 A	PFC Diode	
D45, D47, D49	FWD	650 V	6 A	PFC Sw. Protection Diode	
C25, C27, C29	Capacitor	630 V		Capacitor (PFC)	
Rt	Thermistor			Thermistor	

Packaging instruction				
Standard packaging quantity (SPQ) 100	>SPQ	Standard	<SPQ	Sample

Handling instruction
Handling instructions for *flow* 1 packages see vincotech.com website.

Package data
Package data for *flow* 1 packages see vincotech.com website.

UL recognition and file number
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website.

Document No.:	Date:	Modification:	Pages
10-PG06PPA030SJ02-LH92E08T-D1-14	20 Mar. 2020		